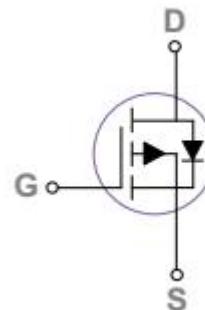


P-Channel Power MOSFET

General Features

- $V_{DS} = -20V, I_D = -90A$
 $R_{DS(ON)} < 2.3 \text{ m}\Omega @ V_{GS} = -10V$
 $R_{DS(ON)} < 2.6 \text{ m}\Omega @ V_{GS} = -4.5V$
- Improved dv/dt capability
- Fast switching
- Good stability and uniformity with high EAS
- Excellent package for good heat dissipation



Schematic diagram

Applications

- Power switching application
- Networking
- Notebook



DFN5X6-8L top view

Absolute Maximum Ratings ($T_c=25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	V_{DS}	-20	V
Gate-Source Voltage	V_{GS}	± 12	V
Drain Current-Continuous ($T_c=25^\circ\text{C}$)	$I_D(25^\circ\text{C})$	-90	A
Drain Current-Continuous ($T_c=100^\circ\text{C}$)	$I_D(100^\circ\text{C})$	-54	A
Pulsed Drain Current	I_{DM}	-360	A
Maximum Power Dissipation ($T_c=25^\circ\text{C}$)	P_D	41.67	W
Derating factor		0.33	W/ $^\circ\text{C}$
Operating Junction and Storage Temperature Range	T_J, T_{STG}	-55 To 150	$^\circ\text{C}$

Thermal Characteristic

Thermal Resistance, Junction-to-Case ^(Note 2)	R _{θJC}	3.0	°C/W
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Electrical Characteristics (T_C=25°C unless otherwise noted)

Parameter	Symbol	Condition	Min	Typ	Max	Unit
Off Characteristics						
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} =0V I _D =250μA	-20	-	-	V
Drain-Source Leakage Current	I _{DSS}	V _{DS} =-20V, V _{GS} =0V, T _J = 25°C	-	-	-1	μA
		V _{DS} =-16V, V _{GS} =0V, T _J = 125°C	-	-	-30	μA
Gate-Body Leakage Current	I _{GSS}	V _{GS} =±12V, V _{DS} =0V	-	-	±500	nA
On Characteristics (Note 3)						
Gate Threshold Voltage	V _{GS(th)}	V _{DS} =V _{GS} , I _D =-250μA	-0.4	-0.6	-1.0	V
Drain-Source On-State Resistance	R _{DSON}	V _{GS} =-10V, I _D = -20A	-	1.8	2.3	mΩ
		V _{GS} =-4.5V, I _D =-20A	-	2.1	2.6	
		V _{GS} =-2.5V, I _D =-20A	-	2.7	3.6	
Forward Transconductance	g _{FS}	V _{DS} =-10V, I _D =-3A	-	30	-	S
Dynamic Characteristics (Note4)						
Input Capacitance	C _{iss}	V _{DS} =-15V, V _{GS} =0V, F=1.0MHz	-	14000	21000	PF
Output Capacitance	C _{oss}		-	1670	2500	PF
Reverse Transfer Capacitance	C _{rss}		-	730	1100	PF
Switching Characteristics (Note 4)						
Turn-on Delay Time	t _{d(on)}	V _{DD} =-15V, I _D =-1A V _{GS} =-4.5V, R _G =25Ω	-	21.2	42	nS
Turn-on Rise Time	t _r		-	20.6	40	nS
Turn-Off Delay Time	t _{d(off)}		-	26	52	nS
Turn-Off Fall Time	t _f		-	400	600	nS
Total Gate Charge	Q _g	V _{DS} =-16V, I _D =-5A, V _{GS} =-4.5V	-	149	225	nC
Gate-Source Charge	Q _{gs}		-	14.4	22	nC
Gate-Drain Charge	Q _{gd}		-	42.8	65	nC
Drain-Source Diode Characteristics						
Diode Forward Voltage (Note 3)	V _{SD}	V _{GS} =0V, I _s =-1A, T _J = 25°C	-	-	-1.0	V
Continuous Source Current	I _s	V _G =V _D =0V, Force Current	-	-	-90	A
Pulsed Source Current	I _{SM}		-	-	-180	A

Notes:

1. Repetitive Rating: Pulse width limited by maximum junction temperature.
2. Surface Mounted on FR4 Board, t ≤ 10 sec.
3. Pulse Test: Pulse Width ≤ 300μs, Duty Cycle ≤ 2%.
4. Guaranteed by design, not subject to production

Typical Electrical and Thermal Characteristics (Curves)

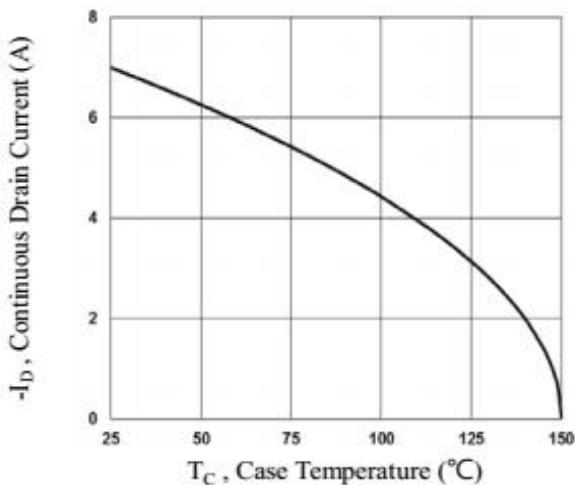


Fig.1 Continuous Drain Current vs. T_c

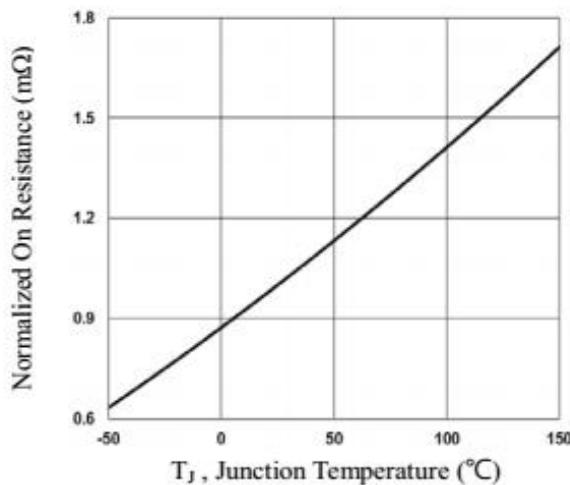


Fig.2 Normalized RD_{SON} vs. T_J

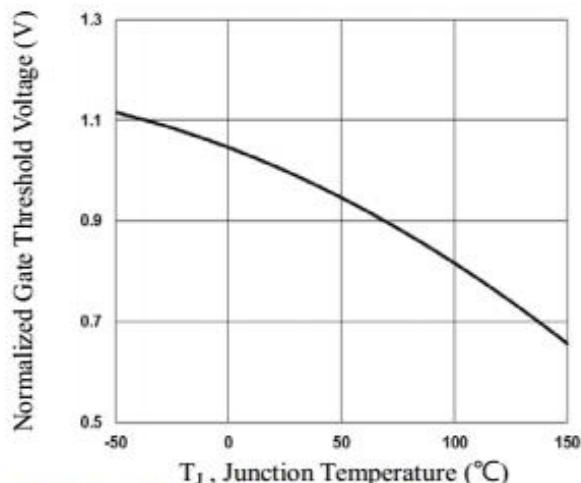


Fig.3 Normalized V_{th} vs. T_J

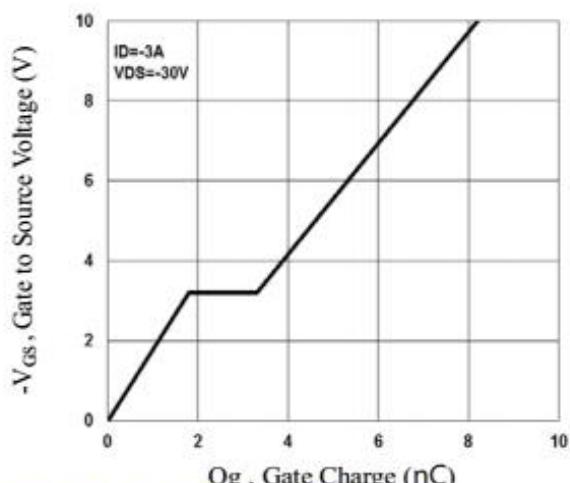


Fig.4 Gate Charge Waveform

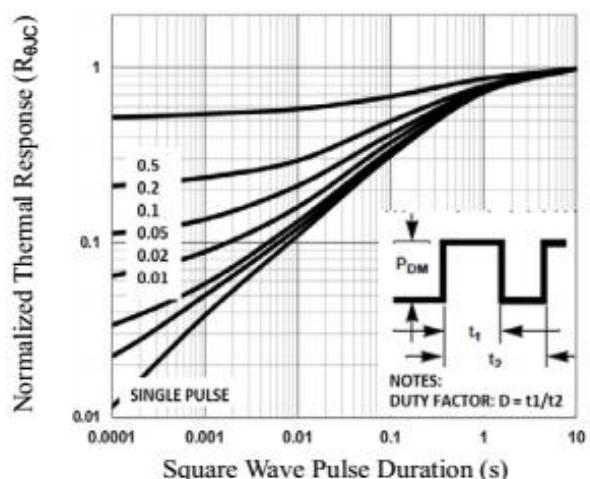


Fig.5 Normalized Transient Impedance

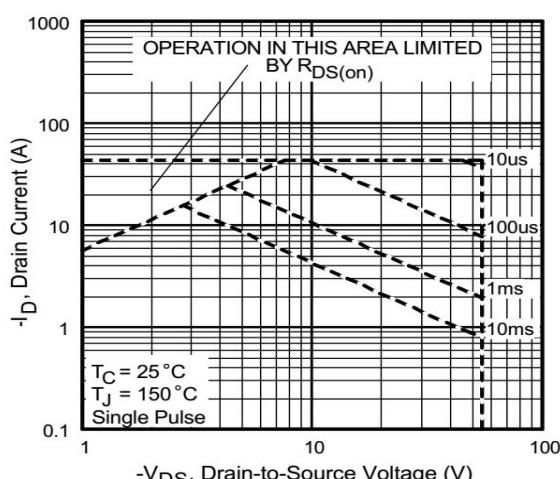


Fig.6 Maximum Safe Operation Area

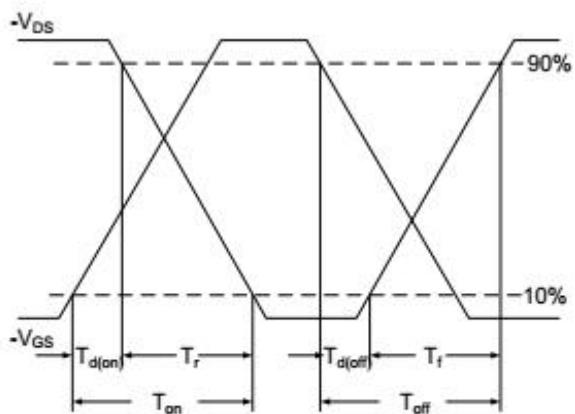


Fig.7 Switching Time Waveform

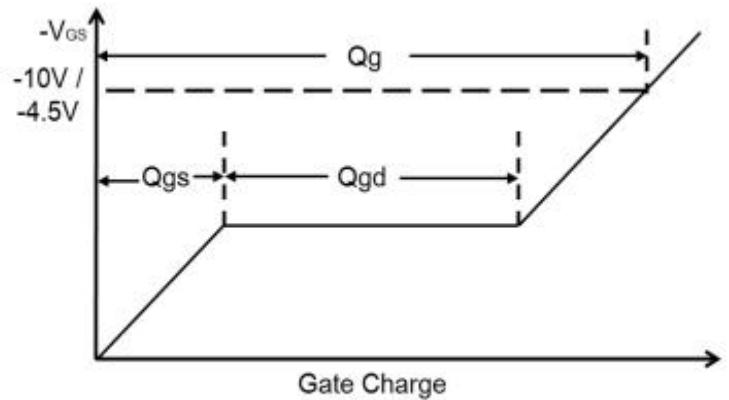
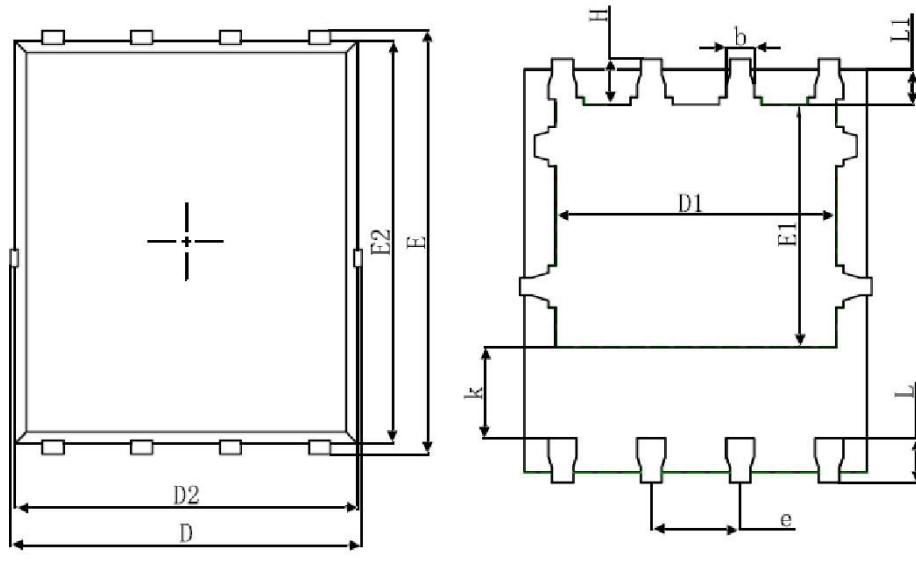


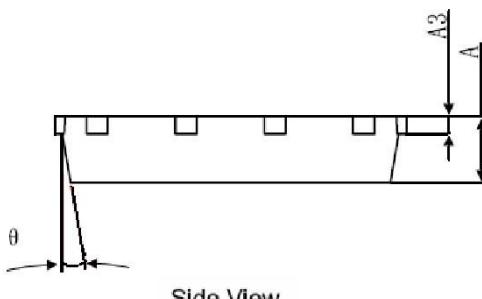
Fig.8 Gate Charge Waveform

DFN5X6-8L Package Information



Top View

Bottom View



Side View

Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	0.900	1.000	0.035	0.039
A3	0.254REF.		0.010REF.	
D	4.944	5.096	0.195	0.201
E	5.974	6.126	0.235	0.241
D1	3.910	4.110	0.154	0.162
E1	3.375	3.575	0.133	0.141
D2	4.824	4.976	0.190	0.196
E2	5.674	5.826	0.223	0.229
k	1.190	1.390	0.047	0.055
b	0.350	0.450	0.014	0.018
e	1.270TYP.		0.050TYP.	
L	0.559	0.711	0.022	0.028
L1	0.424	0.576	0.017	0.023
H	0.574	0.726	0.023	0.029
θ	8°	12°	8°	12°